FEATURES

• 256 Channels
• On-Chip, 14-Bit ADC
• High Performance:
  – Noise: 758 electronRMS (eRMS) with 28-pF Sensor Capacitor in 1.2-pC Range
  – Integral Nonlinearity: ±1.25 LSB with Internal 14-Bit ADC
  – Minimum Scan Time:
    – Normal Mode: 37.9 µs, Internal ADC
    – 2x Binning Mode: 26 µs, Internal ADC
• Integration:
  – Eight Selectable, Full-Scale Ranges:
    – 0.15 pC (min) to 9.6 pC (max)
  – Built-In Correlated Double Sampler
  – 2x Binning for Faster Throughput:
    – Averages Charge of Two Adjacent Channels
  – Pipelined Integration and Read:
    – Allows Data Read During Integration
• Flexibility:
  – Electron and Hole Integration
  – Analog Output Provided for External High-Resolution ADC
• Low Power:
  – 2.9 mW per Channel with ADC
  – 2.3 mW per Channel without ADC
  – 0.1 mW per Channel in Nap Mode
  – Total Power-Down Feature
• 22-mm × 5-mm Gold-Bump Die Suitable for Tape Carrier Package (TCP) or Chip-on-Film (COF)

APPLICATIONS

• Flat-Panel X-Ray Detectors

DESCRIPTION

The AFE0256 is a 256-channel analog front-end (AFE) designed to suit the requirements of flat-panel detector (FPD)-based digital x-ray systems. The device includes 256 integrators, a programmable gain amplifier (PGA) for full-scale charge level selection, a correlated double sampler (CDS) with dual banking, 256:4 analog multiplexers, and four differential output drivers.

The device also features four 14-bit successive-approximation register (SAR) analog-to-digital converters (ADCs) on board. Serial data from the ADCs are available in SPI™ format.

Hardware-selectable integration polarity allows positive or negative charge integration and provides more flexibility in system design. The Nap feature enables substantial power saving that is especially useful in battery-powered systems.

The AFE0256 is available as a 22-mm × 5-mm singulated format with known good gold-bump dies.
Tray, Top Side  
Single Gold-Bump Unit, Back Side

Figure 1. Tray Information
REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<table>
<thead>
<tr>
<th>Changes from Original (December 2012) to Revision A</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>• Changed last Features bullet</td>
<td>1</td>
</tr>
<tr>
<td>• Updated Figure 1</td>
<td>2</td>
</tr>
<tr>
<td>Orderable Device</td>
<td>Status (1)</td>
</tr>
<tr>
<td>------------------</td>
<td>------------</td>
</tr>
<tr>
<td>AFE0256GBTD</td>
<td>ACTIVE</td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:
- **ACTIVE**: Product device recommended for new designs.
- **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.
- **OBSOLETE**: TI has discontinued the production of the device.

(2) **RoHS**: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
- **RoHS Exempt**: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
- **Green**: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) **Lead/Ball Finish** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.
IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2019, Texas Instruments Incorporated